



**QUALCOMM Incorporated**

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9 February 2010

Mr. Ingbert Sigovich and Ms. Susanna Kooistra  
3GPP MCC  
c/o ETSI  
650, route des Lucioles  
06921 Sophia-Antipolis Cedex  
France

Subject: Nomination of candidate for the 3GPP TSG RAN WG5 Vice-Chairman

Dear Mr. Sigovich and Ms. Kooistra:

QUALCOMM is pleased to nominate Mr. Pradeep Gowda for the position of vice-chair of 3GPP TSG-RAN WG5. Pradeep Gowda works for QUALCOMM Incorporated and represents QUALCOMM Incorporated, an ATIS member, in 3GPP.

A brief curriculum vitae of Pradeep Gowda is attached.

Best Regards,

A handwritten signature in black ink, appearing to read 'Edward G. Tiedemann, Jr.' with a stylized flourish at the end.

Edward G. Tiedemann, Jr.  
Senior Vice-President, Engineering  
QUALCOMM Incorporated

## **Pradeep Gowda**

Pradeep has been working at QUALCOMM since 2001 and has been involved in RF and Layer 1 conformance testing of cdma2000, WCDMA, and GERAN chipsets. For the last 5 years he has been leading RF and Layer 1 system testing activities, and coordinating and planning Layer 1 and RF verification activities with cross functional teams (involving Systems, SW, and HW engineers).

In November 2008, Pradeep started attending RAN WG5 meetings and has been actively contributing to RF and Layer 1 aspects of HSPA, DC-HSDPA, and LTE specifications. During his time as a RAN5 RF delegate, he actively contributed and led the completion of HSPA Type3i WI, coordinated the completion of RF aspects of DC-HSDPA specifications, and contributed to the TDD and FDD aspects of LTE specifications.

Pradeep graduated in 2001 with a Master's degree in Electrical Engineering from the State University of New York Buffalo, USA.